

S = 0.38μm GOLD/GXT
ON CONTACT AREA
2μm MIN MATTE
TIN ON TAIL

2µm MIN MATTE
TIN ON TAIL

G = 0.76 μ m GOLD/GXT
ON CONTACT AREA
2 μ m MIN MATTE
TIN ON TAIL

F = GOLD FASH
ON CONTACT AREA
2μm MIN MATTE

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC UL 94V-0, COLOR BLACK
2. MATERIAL TERMINAL: COPPER ALLOY
3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.

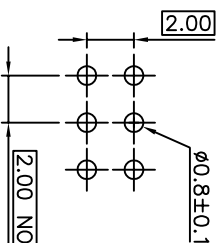
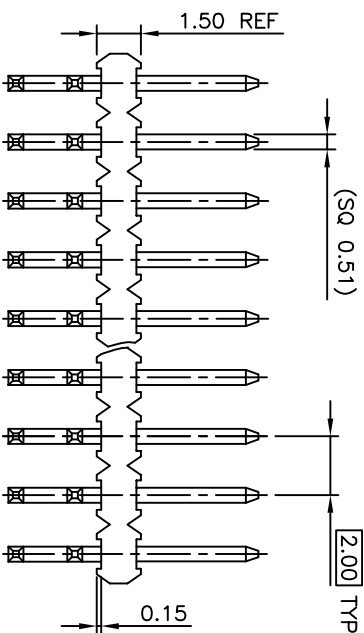
= PLASTIC BOX
U = TUBE AVAILABLE FROM 06 TO 50 POS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

- MEETS PACKAGING SPECS AS PER GS-14-920
- THIS PRODUCT MEETS EUROPEAN DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DISCRIBED
IN GS-47-0004



mat'l. code		surface		tolerance		projection		product family	
		ISO 1302	ISO 406	ISO 101			MINITEK		
ltr	ecm no	dr	date	tolerances unless otherwise specified				title	
A	F10338	LMU	03.10.01	angles		X ±0.3		UNSHR HEADER	
B	F04-0351	JCO	05.01.13	linear		X.X ±0.13		RIGHT ANGLE TMT	
C	F06-0211	LMU	06.07.05			X.XX ±0.05		scale 1:1	
D	F08-0145	ELA	17.04.08	dr	L. MLIN		dwg no		
E	B-19190	LMU	14.10.24	eng	COMPAGNON		sheet 1 of 1		
				chr			size		
				qppd	JM.C		A3		
sheet	revision						CUSTOMER Drawing		
index	sheet								